



THE DATASHEET OF SSTUB32866CHLF





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SSTUB32866CHLF

Category:	
Generic Part:	SSTUB32866C
Market Group:	RDIMM
Description:	1.8V REG. BUFFER (800 MHZ)



Parameters

Package	CABGA 96 (BFG96)
Speed	NA
Temperature	C
Voltage	3.3 V
Status	Active
Sample	No
Minimum Order Quantity	270
Factory Order Increment	270

Distributor Inventory

No Pricing information is available from our Distributors at this time.

Documents


Type	Title	Size	Revision Date
Product Change Notice	PCN# : A-0607-02 IDT Penang as Alternate Assembly Facility for ICS CVBGA and FPBGA	100 KB	07/27/2006
	PCN# A-0607-05 Green Mold Compound KMC3580 for BGA	195 KB	08/30/2006
	PCN# : A-0610-02 ASAT China as Alternate Facility for CABGA/CV BGA/FPBGA/TQFP/PQFP	253 KB	10/19/2006

Package

Description	CHIP ARRAY BGA 5.5 X 13.5 MM X 0.8 MM PI
Class	PLASTIC
Moisture Sensitivity Level (MSL)	3
Category	Green
Moisture Exposure Floor Life	168 hrs. @ <30°C/60%RH
Peak Reflow Temperature	260°C
Rebake Conditions	48 hrs.@125°C
Length	13.5
Mark	H
Width	5.5
Pitch	0.8
Thickness	1.4
Status	Active

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